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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	2475
Number of Logic Elements/Cells	39600
Total RAM Bits	1161216
Number of I/O	328
Number of Gates	-
Voltage - Supply	0.97V ~ 1.03V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-BGA
Supplier Device Package	484-FBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4ce40f23c8ln

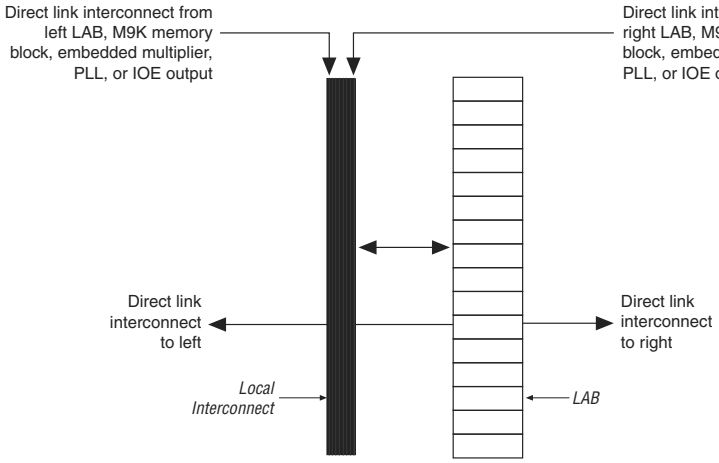
- Cyclone IV GX devices offer up to eight high-speed transceivers that provide:
  - Data rates up to 3.125 Gbps
  - 8B/10B encoder/decoder
  - 8-bit or 10-bit physical media attachment (PMA) to physical coding sublayer (PCS) interface
  - Byte serializer/deserializer (SERDES)
  - Word aligner
  - Rate matching FIFO
  - TX bit slipper for Common Public Radio Interface (CPRI)
  - Electrical idle
  - Dynamic channel reconfiguration allowing you to change data rates and protocols on-the-fly
  - Static equalization and pre-emphasis for superior signal integrity
  - 150 mW per channel power consumption
  - Flexible clocking structure to support multiple protocols in a single transceiver block
- Cyclone IV GX devices offer dedicated hard IP for PCI Express (PIPE) (PCIe) Gen 1:
  - ×1, ×2, and ×4 lane configurations
  - End-point and root-port configurations
  - Up to 256-byte payload
  - One virtual channel
  - 2 KB retry buffer
  - 4 KB receiver (Rx) buffer
- Cyclone IV GX devices offer a wide range of protocol support:
  - PCIe (PIPE) Gen 1 ×1, ×2, and ×4 (2.5 Gbps)
  - Gigabit Ethernet (1.25 Gbps)
  - CPRI (up to 3.072 Gbps)
  - XAUI (3.125 Gbps)
  - Triple rate serial digital interface (SDI) (up to 2.97 Gbps)
  - Serial RapidIO (3.125 Gbps)
  - Basic mode (up to 3.125 Gbps)
  - V-by-One (up to 3.0 Gbps)
  - DisplayPort (2.7 Gbps)
  - Serial Advanced Technology Attachment (SATA) (up to 3.0 Gbps)
  - OBSAI (up to 3.072 Gbps)

LAB Interconnects

The LAB local interconnect is driven by column and row interconnects and LE outputs in the same LAB. Neighboring LABs, phase-locked loops (PLLs), M9K RAM blocks, and embedded multipliers from the left and right can also drive the local interconnect of a LAB through the direct link connection. The direct link connection feature minimizes the use of row and column interconnects, providing higher performance and flexibility. Each LE can drive up to 48 LEs through fast local and direct link interconnects.

Figure 2–5 shows the direct link connection.

Figure 2–5. Cyclone IV Device Direct Link Connection



LAB Control Signals

Each LAB contains dedicated logic for driving control signals to its LEs. The control signals include:

- Two clocks
- Two clock enables
- Two asynchronous clears
- One synchronous clear
- One synchronous load

You can use up to eight control signals at a time. Register packing and synchronous load cannot be used simultaneously.

Each LAB can have up to four non-global control signals. You can use additional LAB control signals as long as they are global signals.

Synchronous clear and load signals are useful for implementing counters and other functions. The synchronous clear and synchronous load signals are LAB-wide signals that affect all registers in the LAB.

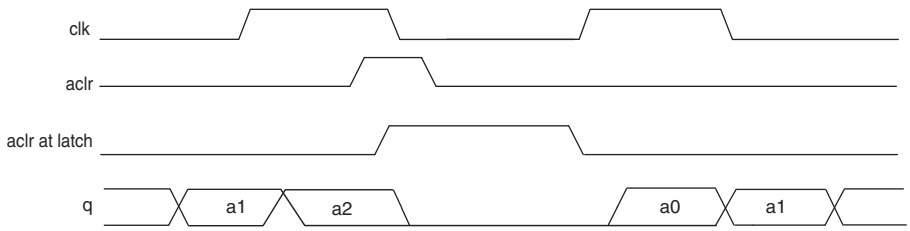
Asynchronous Clear

Cyclone IV devices support asynchronous clears for read address registers, output registers, and output latches only. Input registers other than read address registers are not supported. When applied to output registers, the asynchronous clear signal clears the output registers and the effects are immediately seen. If your RAM does not use output registers, you can still clear the RAM outputs using the output latch asynchronous clear feature.

☞ Asserting asynchronous clear to the read address register during a read operation may corrupt the memory content.

Figure 3–5 shows the functional waveform for the asynchronous clear feature.

Figure 3–5. Output Latch Asynchronous Clear Waveform



☞ You can selectively enable asynchronous clears per logical memory using the Quartus II RAM MegaWizard™ Plug-In Manager.

For more information, refer to the *RAM Megafunction User Guide*.

There are three ways to reset registers in the M9K blocks:

- Power up the device
- Use the `aclr` signal for output register only
- Assert the device-wide reset signal using the **DEV_CLRn** option

Memory Modes

Cyclone IV devices M9K memory blocks allow you to implement fully-synchronous SRAM memory in multiple modes of operation. Cyclone IV devices M9K memory blocks do not support asynchronous (unregistered) memory inputs.

M9K memory blocks support the following modes:

- Single-port
- Simple dual-port
- True dual-port
- Shift-register
- ROM
- FIFO

- Low time count = 1 cycle
- `rselodd` = 1 effectively equals:
  - High time count = 1.5 cycles
  - Low time count = 1.5 cycles
  - Duty cycle = (1.5/3)% high time count and (1.5/3)% low time count

Scan Chain Description

Cyclone IV PLLs have a 144-bit scan chain.

Table 5–7 lists the number of bits for each component of the PLL.

Table 5–7. Cyclone IV PLL Reprogramming Bits

Block Name	Number of Bits		
	Counter	Other	Total
C4 *(1)*	16	2 *(2)*	18
C3	16	2 *(2)*	18
C2	16	2 *(2)*	18
C1	16	2 *(2)*	18
C0	16	2 *(2)*	18
M	16	2 *(2)*	18
N	16	2 *(2)*	18
Charge Pump	9	0	9
Loop Filter *(3)*	9	0	9
Total number of bits:			144

Notes to Table 5–7:

(1) LSB bit for C4 low-count value is the first bit shifted into the scan chain.

(2) These two control bits include `rbypass`, for bypassing the counter, and `rselodd`, to select the output clock duty cycle.

(3) MSB bit for loop filter is the last bit shifted into the scan chain.

Figure 5–24 shows the scan chain order of the PLL components.

Figure 5–24. PLL Component Scan Chain Order

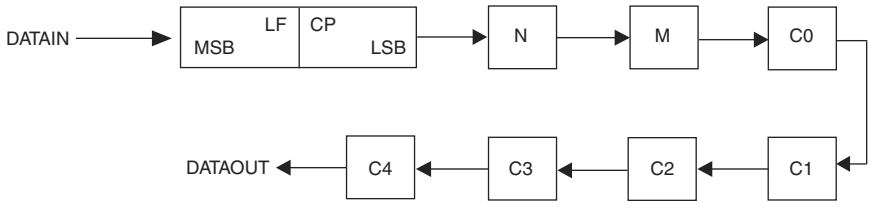
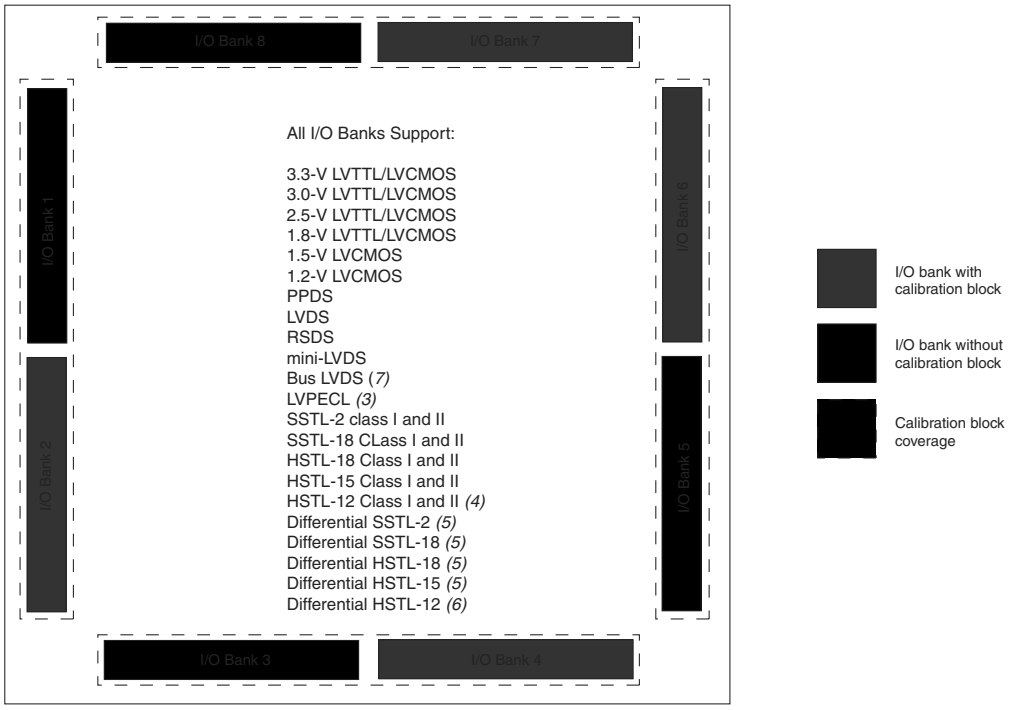


Figure 6–9 shows the overview of Cyclone IV E I/O banks.

Figure 6–9. Cyclone IV E I/O Banks *(1), (2)*



Notes to Figure 6–9:

(1) This is a top view of the silicon die. This is only a graphical representation. For exact pin locations, refer to the pin list and the Quartus II software.

(2) True differential (PPDS, LVDS, mini-LVDS, and RSDS I/O standards) outputs are supported in row I/O banks 1, 2, 5, and 6 only. External resistors are needed for the differential outputs in column I/O banks.

(3) The LVPECL I/O standard is only supported on clock input pins. This I/O standard is not supported on output pins.

(4) The HSTL-12 Class II is supported in column I/O banks 3, 4, 7, and 8 only.

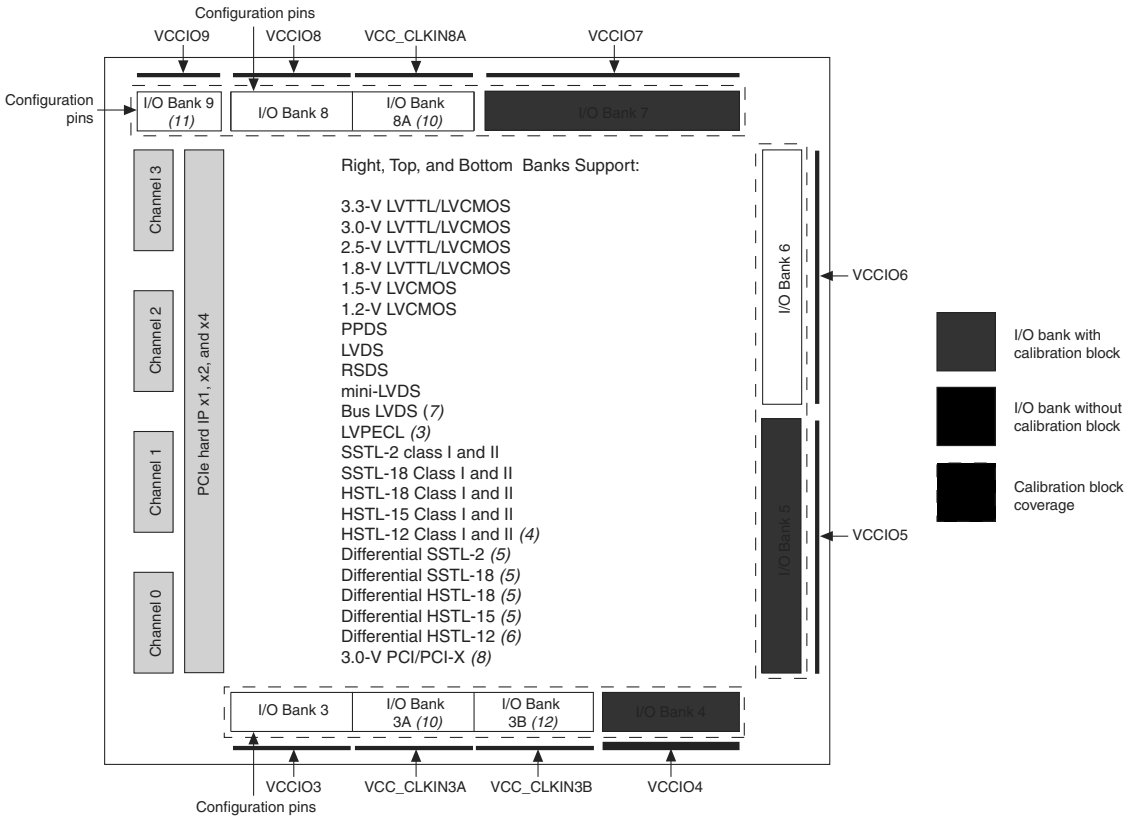
(5) The differential SSTL-18 and SSTL-2, differential HSTL-18, and HSTL-15 I/O standards are supported only on clock input pins and phase-locked loops (PLLs) output clock pins. Differential SSTL-18, differential HSTL-18, and HSTL-15 I/O standards do not support Class II output.

(6) The differential HSTL-12 I/O standard is only supported on clock input pins and PLL output clock pins. Differential HSTL-12 Class II is supported only in column I/O banks 3, 4, 7, and 8.

(7) BLVDS output uses two single-ended outputs with the second output programmed as inverted. BLVDS input uses true LVDS input buffer.

Figure 6–10 and Figure 6–11 show the overview of Cyclone IV GX I/O banks.

Figure 6–10. Cyclone IV GX I/O Banks for EP4CGX15, EP4CGX22, and EP4CGX30 *(1), (2), (9)*



Notes to Figure 6–10:

(1) This is a top view of the silicon die. For exact pin locations, refer to the pin list and the Quartus II software. Channels 2 and 3 are not available in EP4CGX15 and F169 package type in EP4CGX22 and EP4CGX30 devices.

(2) True differential (PPDS, LVDS, mini-LVDS, and RSDS I/O standards) outputs are supported in row I/O banks 5 and 6 only. External resistors are needed for the differential outputs in column I/O banks.

(3) The LVPECL I/O standard is only supported on clock input pins. This I/O standard is not supported on output pins.

(4) The HSTL-12 Class II is supported in column I/O banks 4, 7, and 8.

(5) The differential SSTL-18 and SSTL-2, differential HSTL-18, and HSTL-15 I/O standards are supported only on clock input pins and phase-locked loops (PLLs) output clock pins. PLL output clock pins do not support Class II interface type of differential SSTL-18, HSTL-18, HSTL-15, and HSTL-12 I/O standards.

(6) The differential HSTL-12 I/O standard is only supported on clock input pins and PLL output clock pins. Differential HSTL-12 Class II is supported only in column I/O banks 4, 7, and 8.

(7) BLVDS output uses two single-ended outputs with the second output programmed as inverted. BLVDS input uses the LVDS input buffer.

(8) The PCI-X I/O standard does not meet the IV curve requirement at the linear region.

(9) The OCT block is located in the shaded banks 4, 5, and 7.

(10) There are two dedicated clock input I/O banks (I/O bank 3A and I/O bank 8A) that can be used for either high-speed serial interface (HSSI) input reference clock pins or clock input pins.

(11) There are dual-purpose I/O pins in bank 9. If input pins with VREF I/O standards are used on these dual-purpose I/O pins during user mode, they share the VREF pin in bank 8.These dual-purpose IO pins in bank 9 when used in user mode also support R_S OCT without calibration and they share the OCT block with bank 8.

(12) There are four dedicated clock input in I/O bank 3B for the EP4CGX30F484 device that can be used for either HSSI input reference clock pins or clock input pins.

LVPECL I/O Support in Cyclone IV Devices

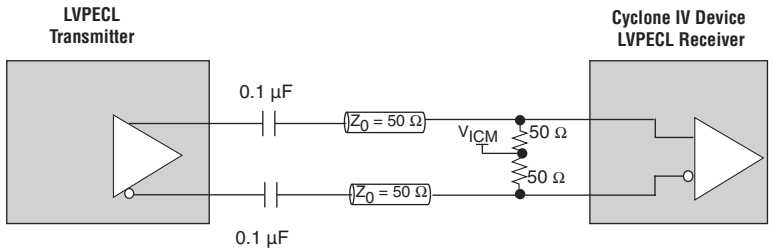
The LVPECL I/O standard is a differential interface standard that requires a 2.5-V V_{CCIO}. This standard is used in applications involving video graphics, telecommunications, data communications, and clock distribution. Cyclone IV devices support the LVPECL input standard at the dedicated clock input pins only. The LVPECL receiver requires an external 100-Ω termination resistor between the two signals at the input buffer.

For the LVPECL I/O standard electrical specification, refer to the *Cyclone IV Device Datasheet* chapter.

AC coupling is required when the LVPECL common mode voltage of the output buffer is higher than the Cyclone IV devices LVPECL input common mode voltage.

Figure 6–18 shows the AC-coupled termination scheme. The 50-Ω resistors used at the receiver are external to the device. DC-coupled LVPECL is supported if the LVPECL output common mode voltage is in the Cyclone IV devices LVPECL input buffer specification (refer to Figure 6–19).

Figure 6–18. LVPECL AC-Coupled Termination *(1)*

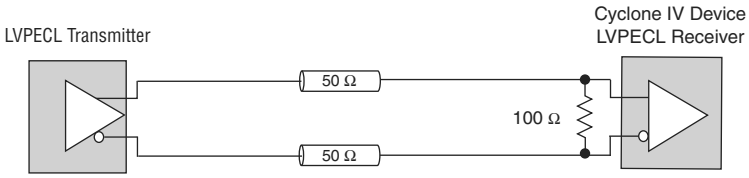


Note to Figure 6–18:

(1) The LVPECL AC-coupled termination is applicable only when an Altera FPGA transmitter is used.

Figure 6–19 shows the LVPECL DC-coupled termination.

Figure 6–19. LVPECL DC-Coupled Termination *(1)*



Note to Figure 6–19:

(1) The LVPECL DC-coupled termination is applicable only when an Altera FPGA transmitter is used.

Table 6–11. High-Speed I/O Timing Definitions (Part 2 of 2)

Parameter	Symbol	Description
Input jitter tolerance (peak-to-peak)	—	Allowed input jitter on the input clock to the PLL that is tolerable while maintaining PLL lock.
Output jitter (peak-to-peak)	—	Peak-to-peak output jitter from the PLL.

Note to Table 6–11:

(1) The TCCS specification applies to the entire bank of differential I/O as long as the SERDES logic is placed in the logic array block (LAB) adjacent to the output pins.

Figure 6–21. High-Speed I/O Timing Diagram

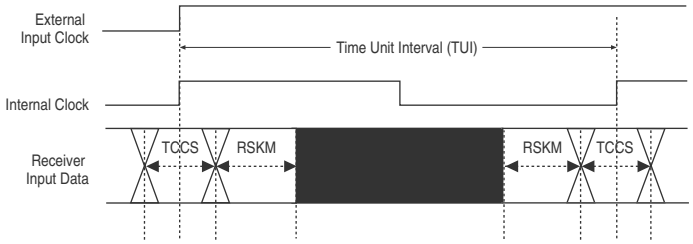
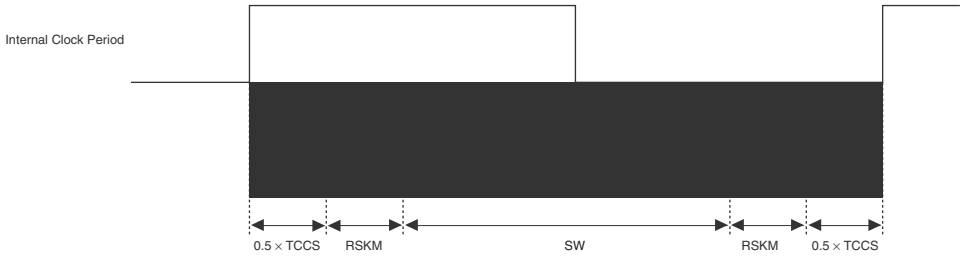


Figure 6–22 shows the Cyclone IV devices high-speed I/O timing budget.

Figure 6–22. Cyclone IV Devices High-Speed I/O Timing Budget *(1)*



Note to Figure 6–22:

(1) The equation for the high-speed I/O timing budget is:
eriod = $0.5 \times TCCS + RSKM + SW + RSKM + 0.5 \times TCCS$

For more information, refer to the *Cyclone IV Device Datasheet* chapter.

Design Guidelines

This section provides guidelines for designing with Cyclone IV devices.

Differential Pad Placement Guidelines

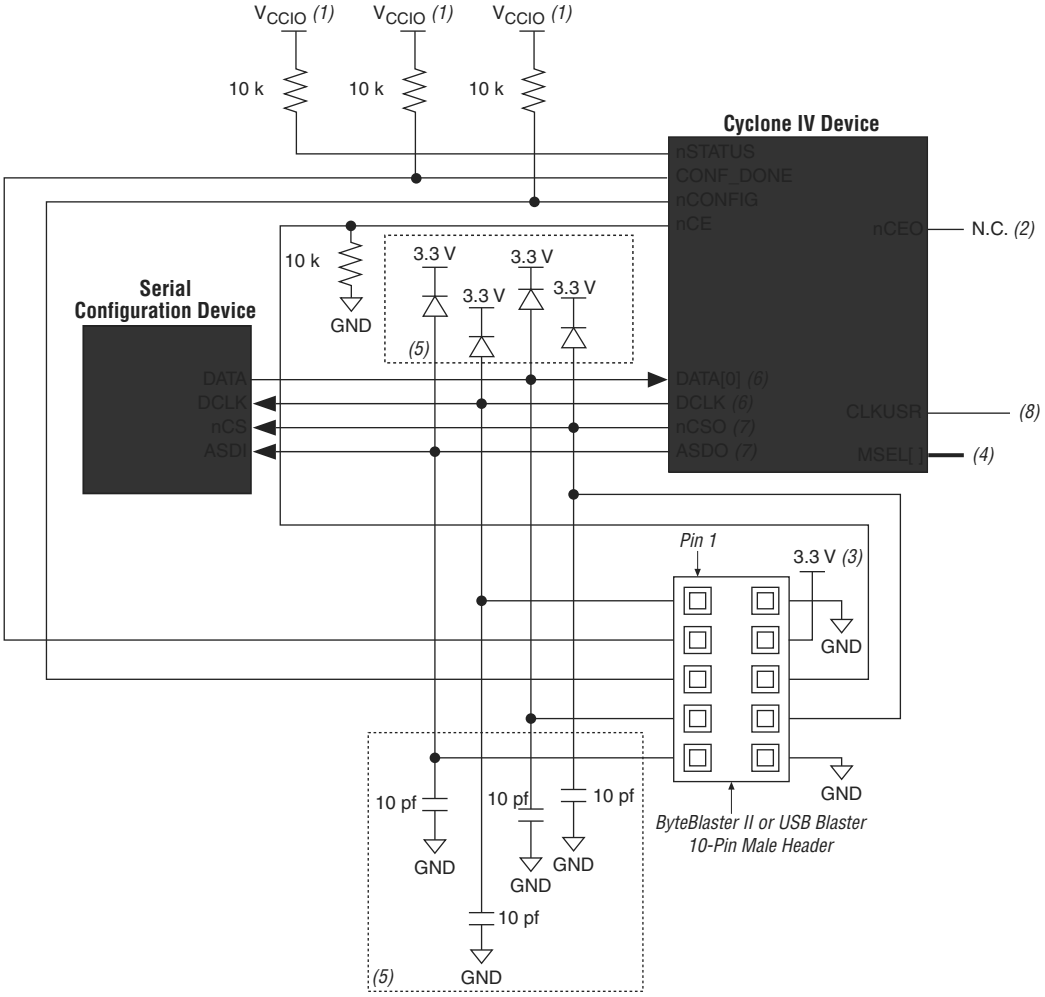
To maintain an acceptable noise level on the V_{CCIO} supply, you must observe some restrictions on the placement of single-ended I/O pins in relation to differential pads.

For guidelines on placing single-ended pads with respect to differential pads in Cyclone IV devices, refer to "Pad Placement and DC Guidelines" on page 6–23.

For more information about the USB-Blaster download cable, refer to the *USB-Blaster Download Cable User Guide*. For more information about the ByteBlaster II download cable, refer to the *ByteBlaster II Download Cable User Guide*.

Figure 8–6 shows the download cable connections to the serial configuration device.

Figure 8–6. In-System Programming of Serial Configuration Devices



Notes to Figure 8–6:

(1) Connect these pull-up resistors to the V_{CCIO} supply of the bank in which the pin resides.

(2) The nCEO pin is left unconnected or used as a user I/O pin when it does not feed the nCE pin of another device.

(3) Power up the V_{CC} of the ByteBlaster II or USB-Blaster download cable with the 3.3-V supply.

(4) The MSEL pin settings vary for different configuration voltage standards and POR time. To connect the MSEL pins, refer to Table 8–3 on page 8–8, Table 8–4 on page 8–8, and Table 8–5 on page 8–9. Connect the MSEL pins directly to V_{CCA} or GND.

(5) The diodes and capacitors must be placed as close as possible to the Cyclone IV device. You must ensure that the diodes and capacitors maintain a maximum AC voltage of 4.1 V. The external diodes and capacitors are required to prevent damage to the Cyclone IV device AS configuration input pins due to possible overshoot when programming the serial configuration device with a download cable. Altera recommends using the Schottky diode, which has a relatively lower forward diode voltage (VF) than the switching and Zener diodes, for effective voltage clamping.

(6) When cascading Cyclone IV devices in a multi-device AS configuration, connect the repeater buffers between the master and slave devices for DATA[0] and DCLK. All I/O inputs must maintain a maximum AC voltage of 4.1 V. The output resistance of the repeater buffers must fit the maximum overshoot equation outlined in "Configuration and JTAG Pin I/O Requirements" on page 8–5.

(7) These pins are dual-purpose I/O pins. The nCSO pin functions as FLASH_nCE pin in AP mode. The ASDO pin functions as DATA[1] pin in AP and FPP modes.

(8) Only Cyclone IV GX devices have an option to select CLKUSR (40 MHz maximum) as the external clock source for DCLK.

The nSTATUS and CONF_DONE pins on all target devices are connected together with external pull-up resistors, as shown in Figure 8–8 on page 8–26 and Figure 8–9 on page 8–27. These pins are open-drain bidirectional pins on the devices. When the first device asserts nCEO (after receiving all its configuration data), it releases its CONF_DONE pin. However, the subsequent devices in the chain keep this shared CONF_DONE line low until they receive their configuration data. When all target devices in the chain receive their configuration data and release CONF_DONE, the pull-up resistor drives a high level on this line and all devices simultaneously enter initialization mode.

Guidelines for Connecting Parallel Flash to Cyclone IV E Devices for an AP Interface

For single- and multi-device AP configuration, the board trace length and loading between the supported parallel flash and Cyclone IV E devices must follow the recommendations listed in Table 8–11. These recommendations also apply to an AP configuration with multiple bus masters.

Table 8–11. Maximum Trace Length and Loading for AP Configuration

Cyclone IV E AP Pins	Maximum Board Trace Length from Cyclone IV E Device to Flash Device (inches)	Maximum Board Load (pF)
DCLK	6	15
DATA[15..0]	6	30
PADD[23..0]	6	30
nRESET	6	30
Flash_nCE	6	30
nOE	6	30
nAVD	6	30
nWE	6	30
I/O (1)	6	30

Note to Table 8–11:

(1) The AP configuration ignores the WAIT signal from the flash during configuration mode. However, if you are accessing flash during user mode with user logic, you can optionally use the normal I/O to monitor the WAIT signal from the Micron P30 or P33 flash.

Configuring With Multiple Bus Masters

Similar to the AS configuration scheme, the AP configuration scheme supports multiple bus masters for the parallel flash. For another master to take control of the AP configuration bus, the master must assert nCONFIG low for at least 500 ns to reset the master Cyclone IV E device and override the weak 10-kΩ pull-down resistor on the nCE pin. This resets the master Cyclone IV E device and causes it to tri-state its AP configuration bus. The other master device then takes control of the AP configuration bus. After the other master device is done, it releases the AP configuration bus, then releases the nCE pin, and finally pulses nCONFIG low to restart the configuration.

In the AP configuration scheme, multiple masters share the parallel flash. Similar to the AS configuration scheme, the bus control is negotiated by the nCE pin.

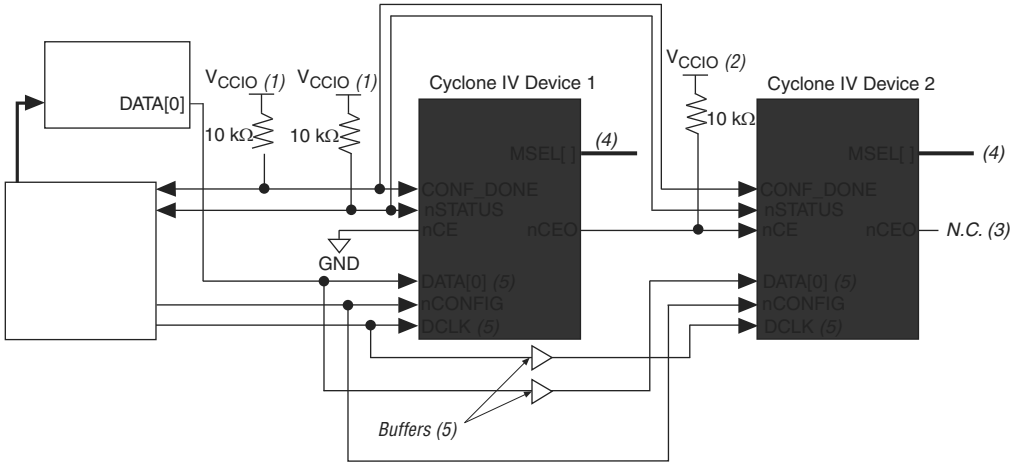
To ensure DCLK and DATA[0] are not left floating at the end of configuration, the MAX II device must drive them either high or low, whichever is convenient on your board. The DATA[0] pin is available as a user I/O pin after configuration. In the PS scheme, the DATA[0] pin is tri-stated by default in user mode and must be driven by the external host device. To change this default option in the Quartus II software, select the **Dual-Purpose Pins** tab of the **Device and Pin Options** dialog box.

The configuration clock (DCLK) speed must be below the specified system frequency to ensure correct configuration. No maximum DCLK period exists, which means you can pause configuration by halting DCLK for an indefinite amount of time.

The external host device can also monitor CONF_DONE and INIT_DONE to ensure successful configuration. The CONF_DONE pin must be monitored by the external device to detect errors and to determine when programming is complete. If all configuration data is sent, but CONF_DONE or INIT_DONE has not gone high, the external device must reconfigure the target device.

Figure 8–14 shows how to configure multiple devices using an external host device. This circuit is similar to the PS configuration circuit for a single device, except that Cyclone IV devices are cascaded for multi-device configuration.

Figure 8–14. Multi-Device PS Configuration Using an External Host



Notes to Figure 8–14:

(1) The pull-up resistor must be connected to a supply that provides an acceptable input signal for all devices in the chain. V_{CC} must be high enough to meet the V_{IH} specification of the I/O on the device and the external host.

(2) Connect the pull-up resistor to the V_{CCIO} supply voltage of the I/O bank in which the nCE pin resides.

(3) The nCEO pin is left unconnected or used as a user I/O pin when it does not feed the nCE pin of another device.

(4) The MSEL pin settings vary for different configuration voltage standards and POR time. To connect the MSEL pins, refer to Table 8–3 on page 8–8, Table 8–4 on page 8–8, and Table 8–5 on page 8–9. Connect the MSEL pins directly to V_{CCA} or GND.

(5) All I/O inputs must maintain a maximum AC voltage of 4.1 V. DATA[0] and DCLK must fit the maximum overshoot outlined in Equation 8–1 on page 8–5.

Remote System Upgrade Mode

In remote update mode, Cyclone IV devices load the factory configuration image after power up. The user-defined factory configuration determines the application configuration to be loaded and triggers a reconfiguration cycle. The factory configuration can also contain application logic.

When used with configuration memory, the remote update mode allows an application configuration to start at any flash sector boundary. Additionally, the remote update mode features a user watchdog timer that can detect functional errors in an application configuration.

Remote Update Mode

In AS configuration scheme, when a Cyclone IV device is first powered up in remote update, it loads the factory configuration located at address `boot_address[23:0] = 24b'0`. Altera recommends storing the factory configuration image for your system at boot address `24b'0`, which corresponds to the start address location `0×000000` in the serial configuration device. A factory configuration image is a bitstream for the Cyclone IV device in your system that is programmed during production and is the fall-back image when an error occurs. This image is stored in non-volatile memory and is never updated or modified using remote access.

When you use the AP configuration in Cyclone IV E devices, the Cyclone IV E device loads the default factory configuration located at the following address after device power-up in remote update mode:
`boot_address[23:0] = 24'h010000 = 24'b1 0000 0000 0000 0000`.

You can change the default factory configuration address to any desired address using the `APFC_BOOT_ADDR` JTAG instruction. The factory configuration image is stored in non-volatile memory and is never updated or modified using remote access. This corresponds to the default start address location `0×010000` represented in 16-bit word addressing (or the updated address if the default address is changed) in the supported parallel flash memory. For more information about the application of the `APFC_BOOT_ADDR` JTAG instruction in AP configuration scheme, refer to the "JTAG Instructions" on page 8–57.

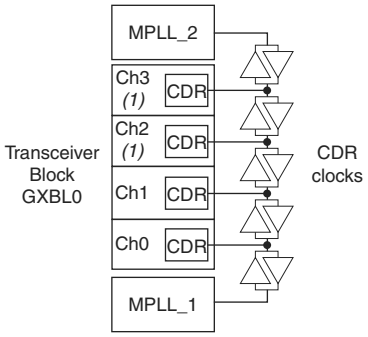
The factory configuration image is user-designed and contains soft logic (Nios II processor or state machine and the remote communication interface) to:

- Process any errors based on status information from the dedicated remote system upgrade circuitry
- Communicate with the remote host and receive new application configurations and store the new configuration data in the local non-volatile memory device
- Determine the application configuration to be loaded into the Cyclone IV device
- Enable or disable the user watchdog timer and load its time-out value (optional)
- Instruct the dedicated remote system upgrade circuitry to start a reconfiguration cycle

The CDR unit in each receiver channel gets the CDR clocks from one of the two multipurpose PLLs directly adjacent to the transceiver block. The CDR clocks distribution network is segmented by bidirectional tri-state buffers as shown in Figure 1–29 and Figure 1–30. This requires the CDR clocks from either one of the two multipurpose PLLs to drive a number of contiguous segmented paths to reach the intended receiver channel. Interleaving the CDR clocks from the two multipurpose PLLs is not supported.

For example, based on Figure 1–29, a combination of `MPLL_1` driving receiver channels 0, 1, and 3, while `MPLL_2` driving receiver channel 2 is not supported. In this case, only one multipurpose PLL can be used for the receiver channels.

Figure 1–29. CDR Clocking for Transceiver Channels in F324 and Smaller Packages



Note to Figure 1–29:

(1) Transceiver channels 2 and 3 are not available for devices in F169 and smaller packages.

Figure 1–30. CDR Clocking for Transceiver Channels in F484 and Larger Packages

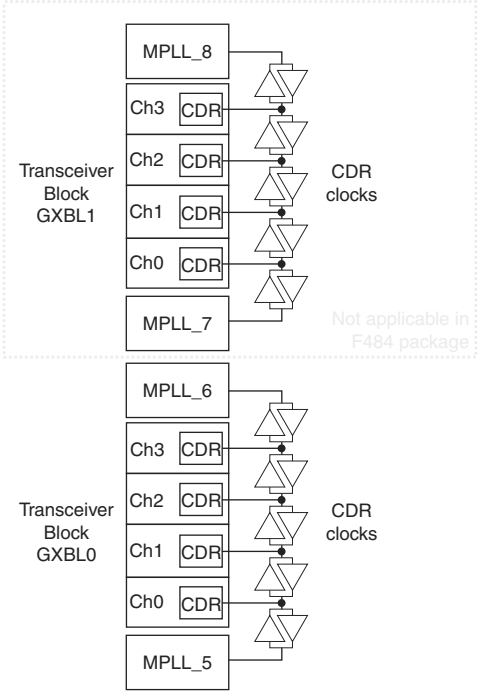


Table 1–26. Transmitter Ports in ALTGX Megafunction for Cyclone IV GX

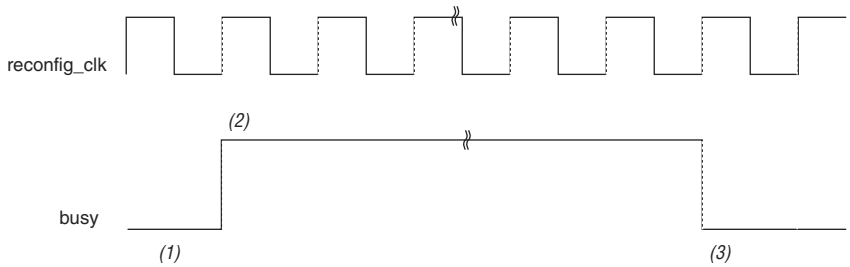
Block	Port Name	Input/ Output	Clock Domain	Description
TX PCS	tx_datain	Input	Synchronous to `tx_clkout` (non-bonded modes) or `coreclkout` (bonded modes)	Parallel data input from the FPGA fabric to the transmitter. ■ Bus width depends on channel width multiplied by number of channels per instance.
	tx_clkout	Output	Clock signal	FPGA fabric-transmitter interface clock in non-bonded modes ■ Each channel has a `tx_clkout` signal that can be used to clock data (`tx_datain`) from the FPGA fabric into the transmitter.
	tx_coreclk	Input	Clock signal	Optional write clock port for the TX phase compensation FIFO.
	tx_phase_comp_fifo_error	Output	Synchronous to `tx_clkout` (non-bonded modes) or `coreclkout` (bonded modes)	TX phase compensation FIFO full or empty indicator. ■ A high level indicates FIFO is either full or empty.
	tx_ctrlenable	Input	Synchronous to `tx_clkout` (non-bonded modes) or `coreclkout` (bonded modes)	8B/10B encoder control or data identifier. This signal passes through the TX Phase Compensation FIFO. ■ A high level to encode data as a /Kx.y/ control code group. ■ A low level to encode data as a /Dx.y/ data code group.
	tx_forcedisp	Input	Synchronous to `tx_clkout` (non-bonded modes) or `coreclkout` (bonded modes)	8B/10B encoder forcing disparity control. This signal passes through the TX Phase Compensation FIFO. ■ A high level to force encoding to positive or negative disparity depending on the `tx_dispval` signal level. ■ A low level to allow default encoding according to the 8B/10B running disparity rules.
	tx_dispval	Input	Synchronous to `tx_clkout` (non-bonded modes) or `coreclkout` (bonded modes)	8B/10B encoder forcing disparity value. This signal passes through the TX Phase Compensation FIFO. ■ A high level to force encoding with a negative disparity code group when `tx_forcedisp` port is asserted high. ■ A low level to force encoding with a positive disparity code group when `tx_forcedisp` port is asserted high.
	tx_invpolarity	Input	Asynchronous signal. Minimum pulse width is two parallel clock cycles.	Transmitter polarity inversion control. ■ A high level to invert the polarity of every bit of the 8- or 10-bit input data to the serializer.
	tx_bitslipboundaryselect	Input	Asynchronous signal.	Control the number of bits to slip before serializer. ■ Valid values from 0 to 9
TX PMA	tx_dataout	Output	—	Transmitter serial data output signal.
	tx_forceelecidle	Input	Asynchronous signal.	Force the transmitter buffer to PIPE electrical idle signal levels. For equivalent signal defined in PIPE 2.00 specification, refer to Table 1–15 on page 1–54.

Table 3–2. Dynamic Reconfiguration Controller Port List (ALTGX_RECONFIG Instance) (Part 3 of 7)

Port Name	Input/ Output	Description
logical_channel_address[n..0]	Input	Enabled by the ALTGX_RECONFIG MegaWizard Plug-In Manager when you enable the **Use 'logical_channel_address' port for Analog controls reconfiguration** option in the **Analog controls** screen. The width of the logical_channel_address port depends on the value you set in the **What is the number of channels controlled by the reconfig controller?** option in the **Reconfiguration settings** screen. This port can be enabled only when the number of channels controlled by the dynamic reconfiguration controller is more than one. Number of channels controlled by the reconfiguration controller — logical_channel_address input port width 2 — logical_channel_address[0] 3–4 — logical_channel_address[1..0] 5–8 — logical_channel_address[2..0] 9–16 — logical_channel_address[3..0]
rx_tx_duplex_sel[1..0]	Input	This is a 2-bit wide signal. You can select this in the **Error checks** screen. The advantage of using this optional port is that it allows you to reconfigure only the transmitter portion of a channel, even if the channel configuration is duplex. For a setting of: ■ rx_tx_duplex_sel[1:0] = 2'b00—the transmitter and receiver portion of the channel is reconfigured. ■ rx_tx_duplex_sel[1:0] = 2'b01—the receiver portion of the channel is reconfigured. ■ rx_tx_duplex_sel[1:0] = 2'b10—the transmitter portion of the channel is reconfigured.

Figure 3–3 shows the timing diagram for a offset cancellation process.

Figure 3–3. Dynamic Reconfiguration Signals Transition during Offset Cancellation



Notes to Figure 3–3:

(1) After device power up, the busy signal remains low for the first reconfig_clk cycle.
(2) The busy signal then gets asserted for the second reconfig_clk cycle, when the dynamic reconfiguration controller initiates the offset cancellation process.
(3) The deassertion of the busy signal indicates the successful completion of the offset cancellation process.

Functional Simulation of the Offset Cancellation Process

You must connect the ALTGX_RECONFIG instances to the ALTGX instances in your design for functional simulation. Functional simulation uses a reduced timing model of the dynamic reconfiguration controller. Therefore, the duration of the offset cancellation process is 16 reconfig_clk clock cycles for functional simulation only. The gxb_powerdown signal must not be asserted during the offset cancellation sequence (for functional simulation and silicon).

Dynamic Reconfiguration Modes

When you enable the dynamic reconfiguration feature, you can reconfigure the following portions of each transceiver channel dynamically, without powering down the other transceiver channels or the FPGA fabric of the device:

- Analog (PMA) controls reconfiguration
- Channel reconfiguration
- PLL reconfiguration

Table 3–3 lists the supported dynamic reconfiguration modes for Cyclone IV GX devices.

Table 3–3. Cyclone IV GX Supported Dynamic Reconfiguration Mode (Part 1 of 2)

Dynamic Reconfiguration Supported Mode	Operational Mode			Quartus II Instances			.mif Requirements
	Transmitter Only	Receiver Only	Transmitter and Receiver Only	ALTGX	ALTGX_RECONFIG	ALTPLL_RECONFIG	
Offset Cancellation	—	✓	✓	✓	✓	—	—
Analog (PMA) Controls Reconfiguration	✓	✓	✓	✓	✓	—	—

The OCT resistance may vary with the variation of temperature and voltage after calibration at device power-up. Use Table 1–10 and Equation 1–1 to determine the final OCT resistance considering the variations after calibration at device power-up. Table 1–10 lists the change percentage of the OCT resistance with voltage and temperature.

Table 1–10. OCT Variation After Calibration at Device Power-Up for Cyclone IV Devices *(1)*

Nominal Voltage	dR/dT (%/°C)	dR/dV (%/mV)
3.0	0.262	–0.026
2.5	0.234	–0.039
1.8	0.219	–0.086
1.5	0.199	–0.136
1.2	0.161	–0.288

Note to Table 1–10:

(1) This specification is not applicable to EP4CGX15, EP4CGX22, and EP4CGX30 devices.

Equation 1–1. Final OCT Resistance *(1), (2), (3), (4), (5), (6)*

$$\Delta R_V = (V_2 - V_1) \times 1000 \times dR/dV \quad (7)$$

$$\Delta R_T = (T_2 - T_1) \times dR/dT \quad (8)$$

$$\text{For } \Delta R_x < 0;\ MF_x = 1/ (|\Delta R_x|/100 + 1) \quad (9)$$

$$\text{For } \Delta R_x > 0;\ MF_x = \Delta R_x/100 + 1 \quad (10)$$

$$MF = MF_V \times MF_T \quad (11)$$

$$R_{final} = R_{initial} \times MF \quad (12)$$

Notes to Equation 1–1:

(1) T_2 is the final temperature.
(2) T_1 is the initial temperature.
(3) MF is multiplication factor.
(4) R_{final} is final resistance.
(5) $R_{initial}$ is initial resistance.
(6) Subscript $_x$ refers to both $_V$ and $_T$.
(7) ΔR_V is a variation of resistance with voltage.
(8) ΔR_T is a variation of resistance with temperature.
(9) dR/dT is the change percentage of resistance with temperature after calibration at device power-up.
(10) dR/dV is the change percentage of resistance with voltage after calibration at device power-up.
(11) V_2 is final voltage.
(12) V_1 is the initial voltage.

Figure 1–4 shows the differential receiver input waveform.

Figure 1–4. Receiver Input Waveform

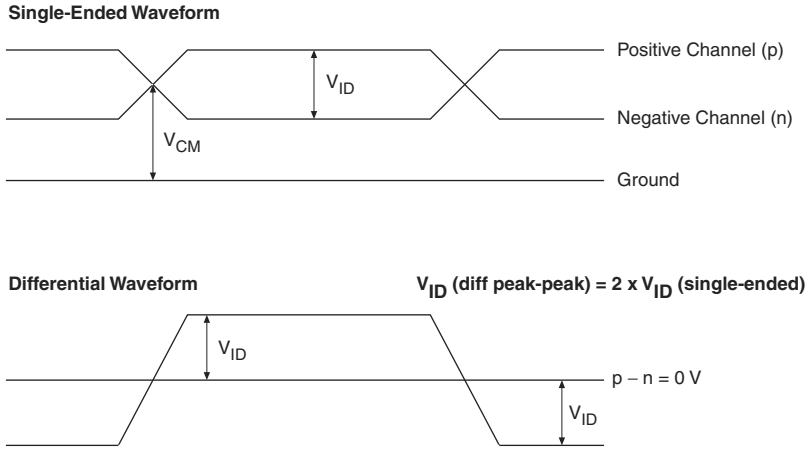


Figure 1–5 shows the transmitter output waveform.

Figure 1–5. Transmitter Output Waveform

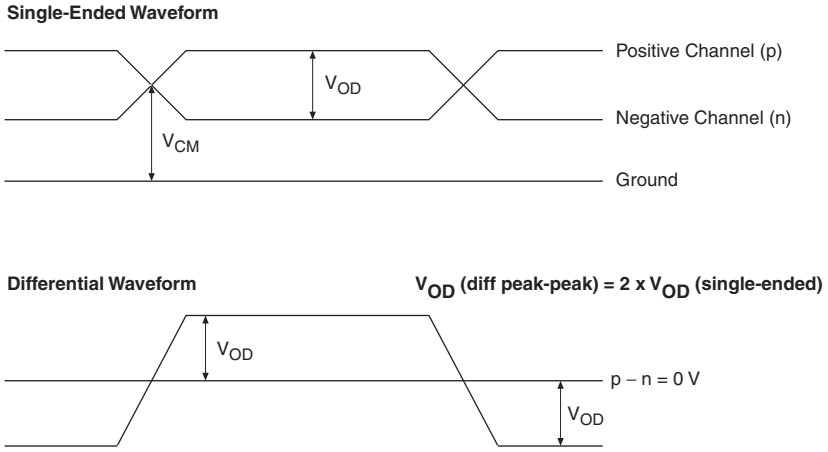


Table 1–22 lists the typical V_{OD} for Tx term that equals 100 Ω.

Table 1–22. Typical V_{OD} Setting, Tx Term = 100 Ω

Symbol	V_{OD} Setting (mV)					
	1	2	3	4 (1)	5	6
V_{OD} differential peak to peak typical (mV)	400	600	800	900	1000	1200

Note to Table 1–22:

(1) This setting is required for compliance with the PCIe protocol.

Table 1–24. Clock Tree Performance for Cyclone IV Devices *(Part 2 of 2)*

Device	Performance								Unit
	C6	C7	C8	C8L (1)	C9L (1)	I7	I8L (1)	A7	
EP4CE55	500	437.5	402	362	265	437.5	362	—	MHz
EP4CE75	500	437.5	402	362	265	437.5	362	—	MHz
EP4CE115	—	437.5	402	362	265	437.5	362	—	MHz
EP4CGX15	500	437.5	402	—	—	437.5	—	—	MHz
EP4CGX22	500	437.5	402	—	—	437.5	—	—	MHz
EP4CGX30	500	437.5	402	—	—	437.5	—	—	MHz
EP4CGX50	500	437.5	402	—	—	437.5	—	—	MHz
EP4CGX75	500	437.5	402	—	—	437.5	—	—	MHz
EP4CGX110	500	437.5	402	—	—	437.5	—	—	MHz
EP4CGX150	500	437.5	402	—	—	437.5	—	—	MHz

Note to Table 1–24:

(1) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades.

PLL Specifications

Table 1–25 lists the PLL specifications for Cyclone IV devices when operating in the commercial junction temperature range (0°C to 85°C), the industrial junction temperature range (–40°C to 100°C), the extended industrial junction temperature range (–40°C to 125°C), and the automotive junction temperature range (–40°C to 125°C). For more information about the PLL block, refer to "Glossary" on page 1–37.

Table 1–25. PLL Specifications for Cyclone IV Devices (1), (2) (Part 1 of 2)

Symbol	Parameter	Min	Typ	Max	Unit
f_{IN} (3)	Input clock frequency (–6, –7, –8 speed grades)	5	—	472.5	MHz
	Input clock frequency (–8L speed grade)	5	—	362	MHz
	Input clock frequency (–9L speed grade)	5	—	265	MHz
f_{INPFD}	PFD input frequency	5	—	325	MHz
f_{VCO} (4)	PLL internal VCO operating range	600	—	1300	MHz
f_{INDUTY}	Input clock duty cycle	40	—	60	%
$t_{INJITTER\_CCJ}$ (5)	Input clock cycle-to-cycle jitter $F_{REF} \geq 100$ MHz	—	—	0.15	UI
	$F_{REF} < 100$ MHz	—	—	±750	ps
f_{OUT_EXT} (external clock output) (3)	PLL output frequency	—	—	472.5	MHz
f_{OUT} (to global clock)	PLL output frequency (–6 speed grade)	—	—	472.5	MHz
	PLL output frequency (–7 speed grade)	—	—	450	MHz
	PLL output frequency (–8 speed grade)	—	—	402.5	MHz
	PLL output frequency (–8L speed grade)	—	—	362	MHz
	PLL output frequency (–9L speed grade)	—	—	265	MHz
$t_{OUTDUTY}$	Duty cycle for external clock output (when set to 50%)	45	50	55	%
t_{LOCK}	Time required to lock from end of device configuration	—	—	1	ms